

Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE

Substitute for Form 1449A/PTO

(use as many sheets as necessary)

UOM 319 PUS

~~CLASS~~
5th CLASS

¹ Unique citation designation number. ² See attached Kinds of U.S. Patent Documents. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to place a check mark here if English language translation is attached.

11/14/03

Substitute for Form 1449B/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)		Complete if Known			
		Applicant Number	10 713 852		
		Filing Date	Filed November 11/14/03		
		First Named Inventor	Asli B. Ucok		
		Group Art Unit	2815		
		Examiner Name	Jasmine Clark		
Sheet	2	of	2	Attorney Docket Number	UOM 0319 PUS

OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS

Examiner Initials	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T*
nbe		AL-SARAWI, SAID P., ET AL., A Review of 3-D Packaging Technology, IEE Transactions On Components, Packaging And Manufacturing Technology, 21, No. 1, pp. 2-14, February 1998	
		SCHUENEMANN, MATTHIAS, ET AL., MEMS Modular Packaging And Interfaces, Proc. Of The 50 th Electronic Components And Technology Conference, pp. 681-688, 2000	
		MILLER, DAVID C., ET AL., Microrelay Packaging Technology Using Flip-Chip Assembly, Proc. Of The 13 th International Conference On Micro-Electro-Mechanical Systems, pp. 265-270, Miyazaki, Japan, January 23-27, 2000	
		MASON, ANDREW, ET AL., A Generic Multi-Element Microsystem For Portable Wireless Applications, Proc. Of The IEEE, pp. 1733-1746, August, 1998	
		GOLDSTEIN, HARRY, Packages Go Vertical, IEEE Spectrum, pp. 46-51, August, 2001	
		GANN, KEITH D., Neo-Stacking Technology, HDI Magazine, December, 1999	
		BAKIR, MUHAMMAD S., ET AL., Sea of Leads (SOL) Ultrahigh Density Wafer-Level Chip Input/Output Interconnections For Gigascale Integration (GSI), IEEE Transactions On Electron Devices, Vol. 50, No. 10, October, 2003	
nbe		MURARI, BRUNO, Bridging The Gap Between The Digital And Real Worlds: The Expanding Role of Analog Interface Technologies, 2003 IEEE International Solid-State Circuits Conference, Plenary Session 1.3, February 10, 2003	

Examiner Signatur	Jasmine Clark	Date Considered	12/08/04
-------------------	---------------	-----------------	----------

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.
¹Unique citation designation number. *Applicant is to place a check mark here if English language Translation is attached.